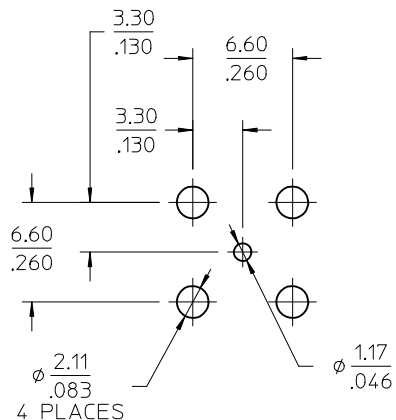
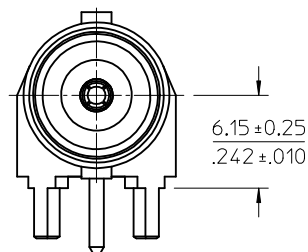


MATERIALS AND FINISHES

BODY: ZINC ALLOY
 PLATED TIN (100 MICRONICHES MIN)
 OVER NICKEL (50 MICRONICHES MIN)
 OVER COPPER (320 MICRONICHES MIN)

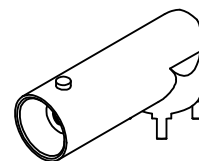
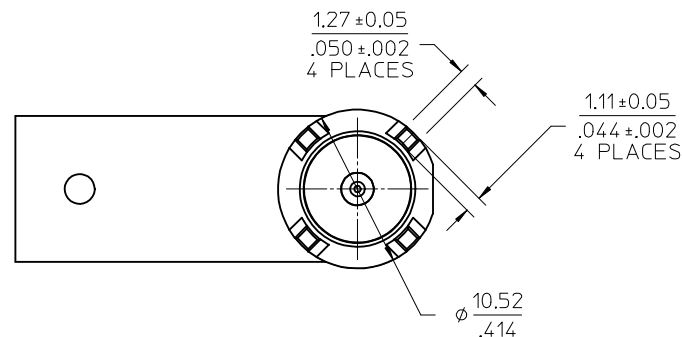
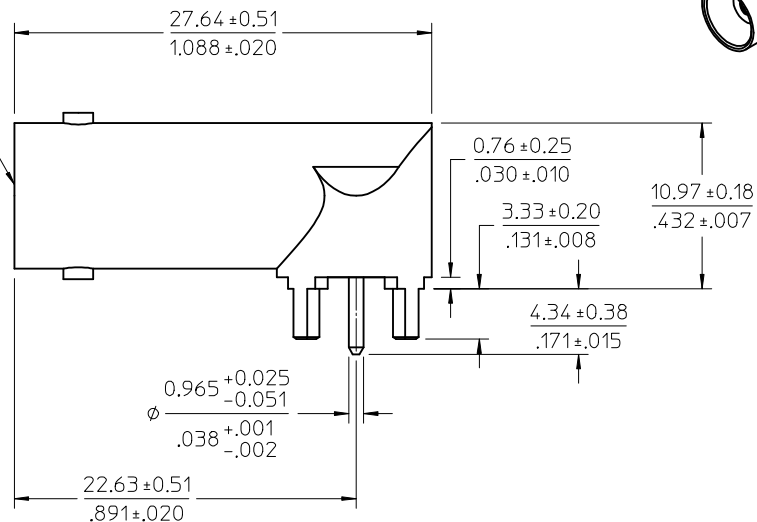
CONTACT: BERYLLIUM COPPER
 PLATED GOLD (SEE TABLE)

INSULATOR: TEFLON



RECOMMENDED PCB
 HOLE PATTERN

BNC JACK
 INTERFACE



MIL-STD-348A, FIG. 301.2	INTERFACE
SPECIFICATION	DESCRIPTION

73171-1341	CONTACT PLATED GOLD 5 MICROINCHES MIN
73171-1340	CONTACT PLATED GOLD 30 MICROINCHES MIN
PART NO.	DESCRIPTION

CHG: REDRAWN & ADDED -1341 PER PDR12/10/210 EC NO: URF2013-0335 DRWN:CWE102 2012/10/26 CHKD: APPR:MHUANG 2012/12/24	DESCRIPTION	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM/IN		SCALE	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION			
			 =0  =0  =0		mm	INCH	DRAWN BY CWE102	DATE 2012/10/26	TITLE BNC JACK R/A PCB 50 OHMS BNC-J/PCB				
				4 PLACES	± ---	± ---	CHECKED BY VINCENT	DATE 2012/10/26					
				3 PLACES	± ---	± ---	APPROVED BY MHUANG 2012/12/24						
				2 PLACES	± ---	± ---							
				1 PLACE	± ---	± ---							
			0 PLACE	± ---	± ---	MATERIAL NO.		DOCUMENT NO.		SHEET NO.			
			ANGULAR ± 2 °			SEE TABLE		SD-73171-134				1 OF 1	
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS										
			SIZE			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX.
 INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION